Amendments to the Specification where added material is shown in underlined type, deleted material is shown in ~~strikeout type~~:

Please replace paragraph **[0006]** with the following amended paragraph:

[0006] The present invention solves the above-identified problems of known surface mountable ~~inductions~~ inductors and transformers by providing a winding and core structure that fully occupies available space and provides for coplanar contact of both the core ends and the winding with an adjacent heat sink.

Please replace paragraph **[0023]** with the following amended paragraph:

[0023] The present invention will now be described in more detail with reference to the Figures. FIGS. 1-3 are several views of an inductive element **100** structured as a transformer or power choke, according to the present invention, having a surface **101** for surface mounting the inductive element on a printed circuit board (PCB) **10**, where FIG. 1 is a perspective view of the inductive element mounted the surface of the PCB, FIGS. 2A and 2B are bottom and side views of inductive element **100**, respectively, and FIG. 3 is a sectional view 3-3. Power choke/transformer **100** has conventional electrical operating characteristics that are a function of ~~it'sconfiguration~~ its configuration, as is well known in the field of power electronics. In addition, the mounting and use of surface-mounted transformers is similarly well known in the field and will not be repeated here.

Please replace paragraph **[0036]** with the following amended paragraph:

[0036] FIG. 6 is a schematic view of the present invention showing the flow of heat from the inductive element **100**. Heat core **110** is provided with two conductive paths to heat sink **150** according to the present invention as follows. The novel path, indicated by the arrows labeled ***Q1*** does not pass through winding **120**. Core **110**, as well as core **400**, **500**, has ends **111** that protrude from elongated portion **113**, which is the central portion of winding **120**. The flow of heat as indicated by arrows ***Q1*** is thus from elongated portion **113**, through ends **111**, and across to the surface **142** of PCB **10** (and optionally on to a heat sink **150**), where it can be transferred away from inductive element **100**. The second path is the conventional path, indicated by the arrows labeled ***Q2***, that passes through winding **120**. Heat generated in elongated portion **113** is conducted

through winding **120**, to PCB **10** (and again optionally to a heat sink **150**). The added paths for heat transfer, and in particular path ***Q1*** that bypasses the winding, greatly ~~increases~~ increase the amount of heat that can be removed from inductive element **100**, thereby enabling the ability to better control the temperature of the inductive element.